

DATA SHEET

AF series 5%, 1%, 0.5%

RoHS compliant & Halogen free

ANTI-SULFURATED CHIP RESISTORS

sizes 0201/0402/0603/0805/1206/1210/1218/2010/2512



Product specification – September 17, 2019 V.5



YAGEO Phícomp

Chip Resistor Surface Mount AF SERIES 0201 to 2512

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<u>SCOPE</u>

This specification describes AF0201 to AF2512 chip resistors with anti-sulfuration capabilities.

APPLICATIONS

- Industrial Equipment
- Power Application
- Networking Application
- High-end Computer & Multimedia Electronics in high sulfur environment
- Automotive electronics

FEATURES

- AEC-Q200 qualified
- Superior resistance against sulfur containing atmosphere
- Halogen free product and production
- RoHS compliant
- Reduces environmentally hazardous waste
- High component and equipment reliability
- Saving of PCB space
- Moisture sensitivity level: MSL I

ORDERING INFORMATION - GLOBAL PART NUMBER

Part number is identified by the series name, size, tolerance, packaging type, temperature coefficient, taping reel and resistance value.

GLOBAL PART NUMBER

AF XXXX X X X XX XXXX L

(1) (2) (3) (4) (5) (6) (7)

(I) SIZE

0201/0402/0603/0805/1206/1210/1218/2010/2512

(2) TOLERANCE

 $D = \pm 0.5\%$

 $F = \pm 1\%$

 $J = \pm 5\%$ (for jumper ordering, use code of J)

(3) PACKAGING TYPE

R = Paper taping reel

K = Embossed plastic tape reel

(4) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(5) TAPING REEL

07 = 7 inch dia. Reel

13 = 13 inch dia. Reel

(6) RESISTANCE VALUE

There are $2\sim4$ digits indicated the resistance value. Letter R/K/M is decimal point. Detailed resistance rules are displayed in the table of "Resistance rule of global part number".

(7) DEFAULT CODE

Letter L is system default code for ordering only (Note)

- Resistance rule of global part

number Resistance coding r	ule Example
XRXX (1 to 9.76 Ω)	R = Ω R5 = .5 Ω 9R76 = 9.76 Ω
XXRX	$10R = 10 \Omega$
(10 to 97.6 Ω)	97R6 = 97.6 Ω
XXXR (100 to 976 Ω)	100R = 100 Ω
XKXX	IK = 1,000 Ω
(1 to 9.76 K Ω)	9K76 = 9760 Ω
XMXX	$IM = I,000,000 \Omega$
(1 to 9.76 MΩ)	9M76= 9,760,000 Ω

ORDERING EXAMPLE

The ordering code for an AF0402 chip resistor, value 100 K Ω with ±1% tolerance, supplied in 7-inch tape reel with 10Kpcs quantity is: AF0402FR-07100KL.

NOTE

- All our R-Chip products are RoHS compliant and Halogen free. "LFP" of the internal 2D reel label states "Lead-Free Process"
- 2. On customized label, "LFP" or specific symbol can be printed

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Chip Resistor	Surface Mount	AF	SERIES	0201 to 2512			9
MARKING							
AF0201 / AF0402							
Fig. I	No marking						
AF0603 / AF0805 / AF1206 / AF	1210 / AF2010 / AF2	512					
Γig. 2 Value=10 KΩ	E-24 series: 3 dig First two digits fo				digit for number	of zeros	
AF0603							
Prig. 3 Value = 24 Ω	E-24 series: 3 dig One short bar ur			etter			
Fig. 4 Value = 12.4 KΩ	E-96 series: 3 digits, ±1% First two digits for E-96 marking rule and 3rd letter for number of zeros						
AF0805 / AF1206 / AF1210 / AF	2010 / AF2512						
1002 Fig. 5 Value = 10 KΩ	Both E-24 and E- First three digits			•	h digit for numbe	r of zeros	
AF1218							
Fig. 6 Value = 10 K Ω	E-24 series: 3 dig First two digits fo			gure and 3rd	digit for number	of zeros	
1002 Fig. 7 Value = 10 KΩ	Both E-24 and E- First three digits				h digit for numbe	er of zeros	

ΝΟΤΕ

For further marking information, please see special data sheet "Chip resistors marking". Marking of AF series is the same as RC series

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CONSTRUCTION

The resistors are constructed on top of a high grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive glaze. The resistive glaze is covered by a glass.

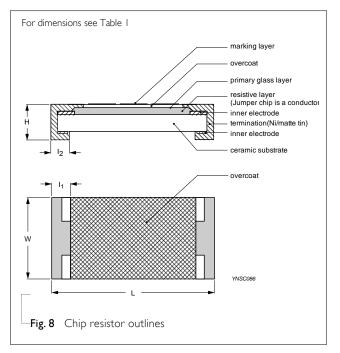
The composition of the glaze is adjusted to give the approximate required resistance value and laser trimming of this resistive glaze achieves the value within tolerance. The whole element is covered by a protective overcoat. Size 0603 and bigger is marked with the resistance value on top. Finally, the two external terminations (Ni / matte tin) are added. See fig.8

DIMENSIONS

Table I For outlines see fig. 8

TYPE	L (mm)	W (mm)	H (mm)	l₁ (mm)	l ₂ (mm)
AF0201	0.60±0.03	0.30±0.03	0.23±0.03	0.12±0.05	0.15±0.05
AF0402	1.00±0.05	0.50±0.05	0.35±0.05	0.20±0.10	0.25±0.10
AF0603	1.60±0.10	0.80±0.10	0.45±0.10	0.25±0.15	0.25±0.15
AF0805	2.00±0.10	1.25±0.10	0.50±0.10	0.35±0.20	0.35±0.20
AF1206	3.10±0.10	1.60±0.10	0.55±0.10	0.45±0.20	0.50±0.20
AF1210	3.10±0.10	2.60±0.15	0.57±0.10	0.45±0.20	0.50±0.20
AF1218	3.10±0.10	4.60±0.10	0.57±0.10	0.45±0.20	0.50±0.20
AF2010	5.00±0.10	2.50±0.15	0.57±0.10	0.55±0.20	0.55±0.20
AF2512	6.35±0.10	3.20±0.15	0.57±0.10	0.60±0.20	0.60±0.20

OUTLINES



ELECTRICAL CHARACTERISTICS

				CHARA	ACTERISTICS		
TYPE	RESISTANCE RANGE	Operating Temperature Range	Max. Working Voltage	Max. Overload Voltage	Dielectric Withstanding Voltage	Temperature Coefficient of Resistance	Jumper Criteria
	±5% (E24),						Rated Current 0.5A
AF0201	Ωto 0MΩ ±0.5%, ±1% (E24/E96), Ω to 0MΩ Zero Ohm Jumper < 0.05Ω		25 V	50 V	50 V	IΩ≤R≤I0Ω,-100/+350 ppm/°C I0Ω < R≤ I0MΩ, ±200 ppm/°C	Max, Current 1.0A
AF0402		-	F0.)/	100.17	100.1/		Rated Current
A10102		-	50 V	100 V	100 V		Max, Current
AF0603	. 50((52.4)		75 V	150 V	150 V		2,0A
	±5% (E24), Ω to 22 MΩ	-				- I Ω≤R≤I0Ω, ±200 ppm/°C	Rated Current 2.0A
AF0805	±0.5%, ±1% (E24/E96), Ω to 10 MΩ		150 V	300 V	300 V	10 Ω < R≤ 10 MΩ, ±100 ppm/°C 10 MΩ < R≤22 MΩ, ±200 ppm/°C	Z.OA Max. Current 5.0A
	$_$ Zero Ohm Jumper < 0.05 Ω	_55 ℃ to +155 ℃				-	Rated Current 2,0A
AF1206			200 V	400 V	500 V		Max. Current 10.0A
	±5% (E24), Ι Ω to ΙΟΜ Ω	-					Rated Current 2,0A
AF1210	± 0.5%, ±1% (E24/E96), I Ω to 10M Zero Ohm Jumper < 0.05Ω		200 V	500 V	500 V		Max. Current 10.0A
	±5% (E24), Ω to MΩ	-				$ \Omega \leq R \leq 0\Omega, \pm 200 \text{ ppm/}^{\circ}C$	Rated Current 2,0A
AF1218	± 0.5%, ±1% (E24/E96), I Ω to I M Zero Ohm Jumper < 0.05Ω		200 V	500 V	500 V	$10\Omega < R \le 10M\Omega, \pm 100 \text{ ppm/°C}$	Max. Current 10.0A
AF2010	$\frac{\pm 5\% \text{ (E24),}}{100 \text{ mper}^{2}}$	-	200 V	500 V	500 V	-	Rated Current 2,0A
AF2512	± 0.5%, ±1% (E24/E96), Ω to 10M Zero Ohm Jumper < 0.05Ω	-	200V	500V	500V		Max. Current 10.0A

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FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles of AF-series is the same as RC-series. Please see the special data sheet "Chip resistors mounting".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PACKING STYLE	REEL DIMENSION	AF0201	AF0402	AF0603/0805/ I 206	AF1210	AF1218/2010/ 2512
Paper taping reel (R)	7" (178 mm)	10,000/20,000	10,000/20,000	5,000	5,000	
	13" (330 mm)	50,000	50,000	20,000	20,000	
Embossed taping reel (K)	7" (178 mm)					4,000

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I. For paper/embossed tape and reel specification/dimensions, please see the special data sheet "Chip resistors packing".

<u>FUNCTIONAL DESCRIPTION</u>

OPERATING TEMPERATURE RANGE

AF0201 - AF2512 Range: -55 °C to + 155 °C (Fig. 7)

POWER RATING

Each type rated power at 70 °C: AF0201=1/20W (0.05W) AF0402=1/16 W (0.0625W) AF0603=1/10 W (0.1W) AF0805=1/8 W (0.125W) AF1206=1/4 W (0.25W) AF1210=1/2W (0.5W) AF1218=1W AF2010=3/4W (0.75W) AF2512=1W

RATED VOLTAGE

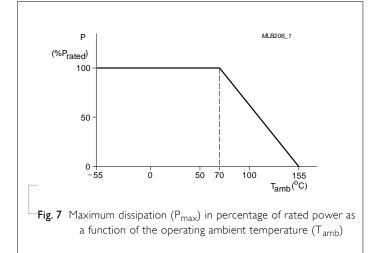
The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

 $V = \sqrt{(P \times R)}$

Where

- V = Continuous rated DC or AC (rms) working voltage (V)
- P = Rated power (W)

 $R = Resistance value (\Omega)$



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TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature	IEC 60115-1 4.8	At +25/–55 °C and +25/+125 °C	Refer to table 2
Coefficient of Resistance	MIL-STD-202 Method 304	Formula:	
(T.C.R.)		$R_2 - R_1$	
		T.C.R= $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$	
		Where t ₁ =+25 °C or specified room temperature	
		t_2 =–55 °C or +125 °C test temperature	
		R _I =resistance at reference temperature in ohms	
		R ₂ =resistance at test temperature in ohms	
Life/Endurance	IEC 60115-1 4.25	At 70±2 °C for 1,000 hours, RCWV applied for	±(1.0%+0.05 Ω)
	MIL-STD-202 Method 108	1.5 hours on, 0.5 hour off, still-air required	<100 m Ω for Jumper
High	MIL-STD-202 Method 108	1,000 hours at 155±3°C	±(1.0%+0.05 Ω)
Temperature Exposure		unpowered	<100 m Ω for Jumper
Moisture Resistance	MIL-STD-202 Method 106	Each temperature / humidity cycle is defined at 8 hours, 3 cycles / 24 hours for 10d. with 25 °C / 65 °C 95% R.H, without steps 7a & 7b,	±(0.5%+0.05 Ω) for 0.5%, 1% tol. ±(1.0%+0.05 Ω) for 5% tol.
		unpowered	<100 m Ω for Jumper
		Parts mounted on test-boards, without condensation on parts	··· ·)- F-
Thermal Shock	MIL-STD-202 Method 107	_55 / +125 ℃	±(0.5%+0.05 Ω) for 0.5%, 1%
		Number of cycles required is 300. Devices mounted	tol. ±(1%+0.05 Ω) for 5% tol.
		Maximum transfer time is 20 seconds. Dwell time is 15 minutes	<100 m Ω for Jumper
Short Time	IEC60115-14.13	2.5 times of rated voltage or maximum overload	±(1.0%+0.05 Ω)
Overload		voltage whichever is less for 5 seconds at room temperature	No visible damage
Bending	IEC 60115-1 4.33	Chips mounted on a 90 mm glass epoxy resin PCB (FR4)	±(1.0%+0.05 Ω) <100 mΩ for Jumper
		Bending: 0201/0402: 5 mm 0603/0805: 3 mm 1206 & above: 2 mm	No visible damage
		Bending time: 60±5 seconds	

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TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Biased Humidity	MIL-STD-202 method 103	1,000 hours; 85° C /85%R.H., 10% of operating power. Measurement at 24±4 hours after test conclusion.	IΩ≤R≤IMΩ: ±(3%+0.05Ω) IMΩ <r≤i0mω: td="" ±(5%+0.05ω)<=""></r≤i0mω:>
Solderability			
- Resistance to Soldering Heat	IEC 60115-1 4.18 MIL-STD-202 Method 215	Condition B, no pre-heat of samples Lead-free solder, 260±5 °C, 10±1 seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	±(0.5%+0.05Ω) for 0.5%, 1% tol. ±(1.0%+0.05Ω) for 5% tol. <50 mΩfor Jumper No visible damage
- Wetting	J-STD-002	Electrical test not required Magnification 10X SMD conditions: (a) Method B, aging 4 hours at 155 °C dry heat, lead-free solder bath at 245 °C (b) Method B, dipping at 215 °C for 3 seconds	Well tinned (≥95% covered) No visible damage
FOS	ASTM-B-809-95* * Modified	Sulfur 750 hours, 105 °C. unpowered	±(4.0%+0.05Ω)

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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 6	Sep. 05, 2019	-	- Updated dimensions
Version 5	Jun. 21, 2016	-	- Update test and requirement
Version 4	Dec. 24, 2015	-	- Update Dielectric Withstanding Voltage& Resistance value
Version 3	Apr. 01, 2015	-	- Modified test and requirements
Version 2	Nov. 20, 2014	-	- Tests and requirement update
Version I	Sep. 27, 2013	-	- Size 0201/1210/1218/2010/2512 extend
Version 0	Jan 07, 2011	-	- First issue of this specification

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